

## Dual N-Channel Enhancement Mode Power MOSFET

## **DESCRIPTION**

The HM6800 uses advanced trench technology to provide excellent  $R_{\rm DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **GENERAL FEATURES**

•  $V_{DS} = 30V, I_D = 5.8A$ 

 $R_{DS(ON)}$  < 59m $\Omega$  @  $V_{GS}$ =2.5V

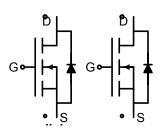
 $R_{DS(ON)} < 45 \text{m}\Omega$  @  $V_{GS}$ =4.5V

 $R_{DS(ON)}$  < 41m $\Omega$  @  $V_{GS}$ =10V

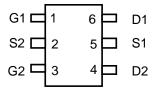
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

## **Application**

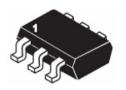
- PWM applications
- Load switch
- ●Power management



## Schematic diagram



## Marking and pin Assignment



SOT23-6L top view

## **Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
H0** **	HM6800	SOT-23-6L	Ø180mm	8 mm	3000 units

# Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	Vgs	±12	V	
Drain Current-Continuous	I <sub>D</sub>	5.8	Α	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	30	Α	
Maximum Power Dissipation	P <sub>D</sub>	1.4	W	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$	

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	1.0	°C/W
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#### Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	33	-	V

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Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	0.7	0.9	1.4	V
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =4A	-	45	59	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.9A	-	34	45	mΩ
		V <sub>GS</sub> =10V, I <sub>D</sub> =2.9A	-	31	41	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =2.9A	10	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C <sub>lss</sub>	\/ -15\/\/ -0\/	-	623	-	PF
Output Capacitance	Coss	$V_{DS}$ =15V, $V_{GS}$ =0V, F=1.0MHz	-	99	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0WHZ	-	77	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t <sub>d(on)</sub>		-	3.3	-	nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =15V,I <sub>D</sub> =2.9A	-	4.8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{GEN}$ =3 $\Omega$	-	26	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	4	-	nS
Total Gate Charge	Qg	\/ -45\/ L -5 0A	-	9.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =15V,I <sub>D</sub> =5.8A,	-	1.5	-	nC
Gate-Drain Charge	$Q_{gd}$	- V <sub>GS</sub> =4.5V	-	3	-	nC
Drain-Source Diode Characteristics	•		•	•	-	-
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =2.9A	-	0.75	1.2	V
Diode Forward Current (Note 2)	Is		-	-	2.9	Α
	•			•		

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

# TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

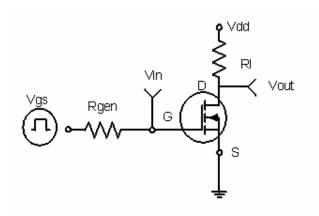


Figure 1:Switching Test Circuit

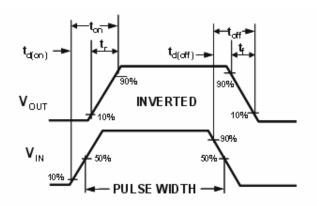
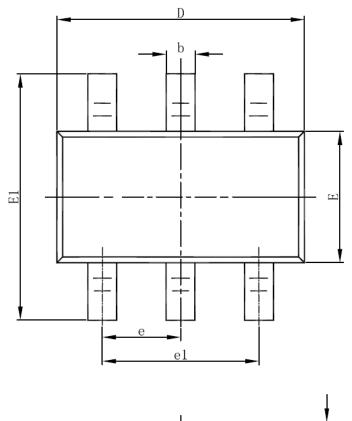
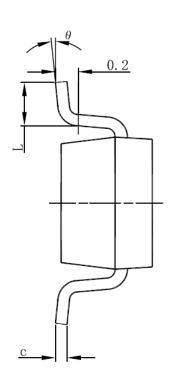
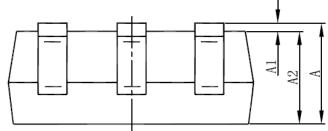


Figure 2:Switching Waveforms

# SOT-23-6L PACKAGE OUTLINE DIMENSIONS







Symbol Dimensions In		n Millimeters	Dimensions	s In Inches
Symbol	Min	Max	Min	Max
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950	(BSC)	0.037	(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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